



F Drafts

Pending

Active

L1: (16489) (205/50-333). CCLs.

L2: (589178) pulse or pulses or pulsed or pulsing

L3: (37993) pulse or pulses or pulsed or pulsating or pulsation

L4: (608700) 12 or 13

L5: (1799436) voltage or current

L6: (139071) 14 near4 15

L7: (3604655) second

L8: (800879) sec

L9: (3752401) 17 or 18

L10: (44297) 19 same 16

L11: (329) 110 and 11

L12: (607286) semiconductor or water

L13: (132) 11 and 112

L14: (18137) taylor.in.

L15: (117) 113 and 114

L16: (1) ("5514258"). PN.

L17: (150571) anode

L18: (1) 116 and 117

L19: (1) ("4466864"). PN.

L20: (1) 119 and 117

L21: (2061) diffuser adj plate

L22: (25) 11 and 121

Failed

Saved

Favorites

Search: US-PPUB-USPAT

DB: ADU

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11 and 121

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Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	I	PT
1	US 20050230262	20051020	17	Electrochemical methods for the formation of protective features on	205/122	204/2224R; 205/255;	Chen, Linlin					
2	US 20050161336	20050728	14	Electroplating apparatus with segmented anode array	205/123	204/198; 204/224R	Woodruff, Daniel J. et al.					
3	US 20050067290	20050331	13	Method and system for automatically controlling a current distribution of a semiconductor plating system workpiece	205/84		Bonkass, Matthias et al.					
4	US 20050061675	20050324	62	Support having workpiece-engaging apparatus and method for forming uniformly thick anodized films on large	205/123	204/201	Black, Martin C. et al.					
5	US 20040077140	20040422	18	Apparatus and method for forming support having workpiece-engaging	438/240	205/80; 257/E21.008;	Andricacos, Panayotis C. et al.					
6	US 20040000487	20040101	15	Method and system for controlling ion distribution during plating of a metal	205/91	204/230.2	Bonkass, Matthias et al.					
7	US 20030116440	20030626	8	Electroplater and method	205/157	205/205; 205/220	Guidi, Richard L. et al.					
8	US 20030057097	20030327	12	Method and apparatus for forming metal layers	205/102		Teal, Stan et al.					
9	US 20020074233	20020620	19	Method and apparatus for low temperature annealing of metallization	205/157	204/274; 205/105;	Ritzdorf, Thomas L. et al.					
10	US 20020000271	20020103	19	METHOD AND APPARATUS FOR LOW-TEMPERATURE ANNEALING OF METALLIZATION	148/518	148/536; 205/157;	RITZDORF, THOMAS et al.					
11	US 7001471 B2	20060221	19	Method and apparatus for low-temperature annealing of metallization	148/518	148/536; 148/679;	Ritzdorf, Thomas L. et al.					
12	US 6974530 B2	20051213		Method and system for controlling ion distribution during plating of a metal	205/96	118/400; 118/429;	Bonkass, Matthias et al.					